

tb_frame_A3_J_ME_S
Rev. D 2004/04/02

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1. 材料 ウエハー : ガラス繊維 15% 入り PBTP (UL94V-0), 黒色
 ピン : 黄銅, サイズ □0.635
2. 嵌合相手 : 5320 シリーズ
3. 使用符号の説明 5332 - N *

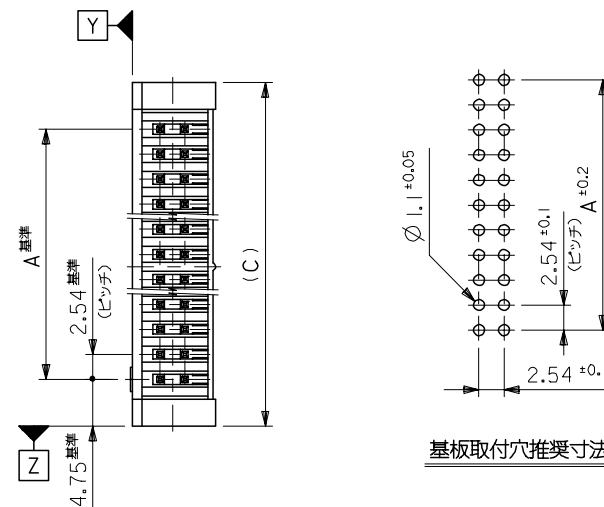
説明 5332 - N *

ベースナンバー _____

極数 _____

ピンのメッキコード _____

	コード:*	△マークの色	コンタクト部	半田付け部	下地メッキ
	GS1	黄	金 0.1μm MIN.	半田 3μm MIN.	ニッケル 1 μm MIN.
	GS3	青	金 0.25μm MIN.		
LEAD-FREE	GS17F	黄	金 0.1μm MIN.	錫 1μm MIN.	
LEAD-FREE	GS37F	青	金 0.25μm MIN.		
LEAD-FREE	T2	黒		錫 1μm MIN.	ニッケル 0.5μm MIN.



基板取付穴推奨寸法

[illegible]

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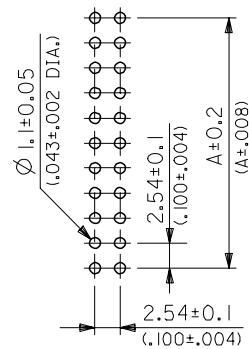
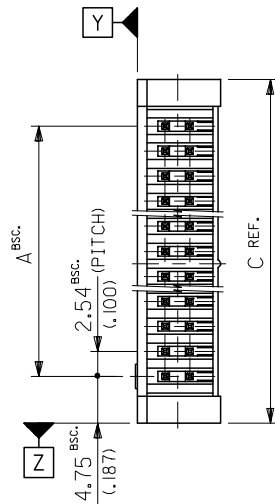
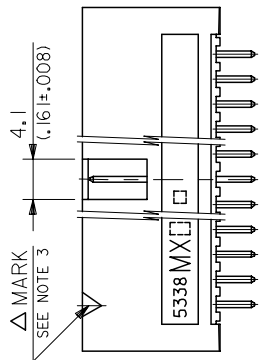
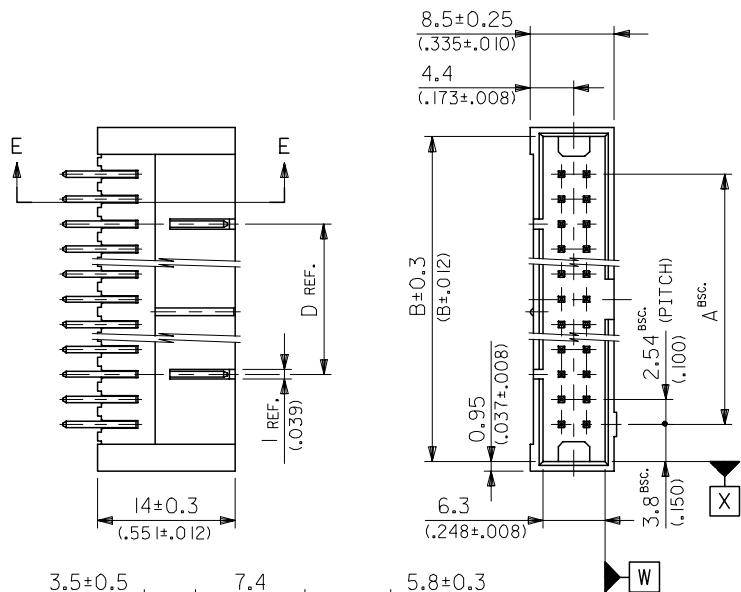
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RECOMMENDED P.C.BOARD PATTERN

NOTES

1. MATERIAL WAFER : G.F. I5% PBT (UL94V-0) , COLOR---BLACK
PINS : BRASS, SIZE--- □0.635(0.25 SQ.)
2. MATES WITH MOLEX CONNECTOR SERIES OF 5320.
3. LEGEND

BASE NUMBER 5332 - N *
CIRCUIT SIZE
PLATING CODE OF PIN

CODE:*	△ MARK COLOR	CONTACT AREA	SOLDER AREA	UNDER PLATE
GS1	YELLOW	GOLD 0.1 μm(0.00004) MIN.	TIN-LEAD 3 μm(0.00012) MIN.	NICKEL 1 μm(0.00004) MIN.
GS3	BLUE	GOLD 0.25 μm(0.00001) MIN.		
LEAD-FREE GS17F	YELLOW	GOLD 0.1 μm(0.00004) MIN.	TIN 1 μm(0.00004) MIN.	NICKEL 0.5 μm(0.00002) MIN.
LEAD-FREE GS37F	BLUE	GOLD 0.25 μm(0.00001) MIN.		
LEAD-FREE T2	BLACK	TIN 1 μm(0.00004) MIN.		

SECT. E-E
(SCALE 3-1)

60	73.66 (2.900)	81.26 (3.200)	83.16 (3.274)	63.50 (2.500)
50	60.96 (2.400)	68.56 (2.700)	70.46 (2.774)	50.80 (2.000)
40	48.26 (1.900)	55.86 (2.200)	57.76 (2.274)	38.10 (1.500)
36	43.18 (1.700)	50.78 (2.000)	52.68 (2.074)	33.02 (1.300)
34	40.64 (1.600)	48.24 (1.900)	50.14 (1.974)	30.48 (1.200)
30	35.56 (1.400)	43.16 (1.700)	45.06 (1.774)	25.40 (1.000)
26	30.48 (1.200)	38.08 (1.500)	39.98 (1.574)	—
20	22.86 (0.900)	30.46 (1.200)	32.36 (1.274)	—
16	17.78 (0.700)	25.38 (1.000)	27.28 (1.074)	—
14	15.24 (0.600)	22.84 (0.900)	24.74 (0.974)	—
10	10.16 (0.400)	17.76 (0.700)	19.66 (0.774)	—
NO. OF CKTS.	DIM. A	DIM. B	DIM. C	DIM. D

REVISED EC NO: J2006-2606 DRAWN: TAKEMOTO CHKD: TANAKA APPR: NUKITA	DESCRIPTION 2006/03/22 2006/03/22 2006/03/24	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	H. HIRAMOTO	1989/07/18	TITLE QIK FLECS WAFER ASSY ST ENGLISH ONLY				
		10 OVER 30 UNDER	± 0.25	M. SASAO						
		30 OVER	± 0.3	H. IKESUGI		MOLEX MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2 OF 2		SD-5332-003			1 OF 2	
K	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

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